

INTERNATIONAL STANDARD



**Universal serial bus interfaces for data and power –
Part 1-2: Common components – USB Power Delivery specification**

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Part 1-2: Common components – USB Power Delivery specification

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This third edition cancels and replaces the second edition published in 2017 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

This bilingual version (2019-03) corresponds to the monolingual English version, published in 2018-04.

The text of this International Standard is based on the following documents:

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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INTRODUCTION

The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.1 and ECNs through 12 June 2017.

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Universal Serial Bus Power Delivery Specification

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